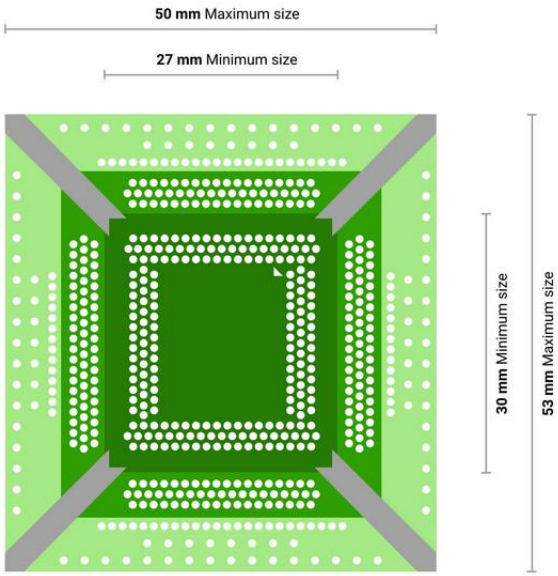

# Future Proof Solder Core - For standardisation without compromise

by Paul Roberts.

## Introduction

Last time we discussed how Phytec offered you the choice of 3 core technologies using the same module footprint. Today we discuss the future and how they have built a solder-down core that not only offers a choice of current processor technologies but also caters for future technologies.

## One Footprint Three Zones




### Must-have signals

The central core features are supported by all modules and provide the interfaces necessary for the development of many products. This zone covers 52 percent of the processor features.

### Preferred Signals

These signals are routed to pins that are currently supported by many processors and should also provide support for future System-on -Modules of the FPSC feature set.

### Proprietary Signals

The third, outer zone allows the use of processor features that are not subject to standardisation and are therefore unique to a processor. This makes it possible to support special and new features of processors.

**Overview of advantages**

- Scalable performance
- High number of guaranteed features
- More cost-effective carrier board design
- State of the art Soldering technology FTGA for high production yield
- Space for the functions of the future
- Start design now and quickly change when new technology becomes available

**Further Information**

Read more details about the FPSC here :-

https://www.phytec.eu/en/produkte/system-on-modules/fpsc/

For more information visit our website: www.hitex.co.uk or get in touch: info@hitex.co.uk. You can also connect with us: LinkedIn